

# **TR7500 SIII 3D** 111

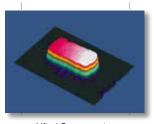
- High Performance Multi-angle 3D PCBA Inspection
- High Defect Coverage Using Hybrid 2D+3D Inspection
- Dual Laser True 3D Profile Measurement
- Accurate Bare Silicon Package Inspection

AUTOMATED
OPTICAL INSPECTION

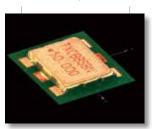
### TR7500 SIII 3D FEATURES

## Defects

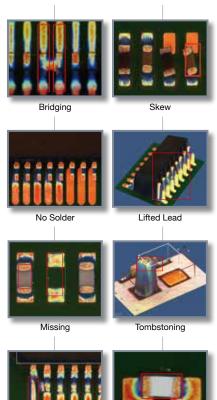
Foreign Material



Lifted Components



Metal-cased Reflective Components



#### TR7500 SIII 3D - High Performance and Total Inspection Coverage

The TR7500 SIII 3D AOI combines the best of 2D and 3D technologies with new generation software in a high performance system for PCB assembly inspection. Built on TRI's high-speed dynamic imaging technology, TR7500 SIII 3D is the ideal AOI for the industry's largest PCBs.

#### Complete Coverage at Full Speed

High resolution images from five multi-angle color cameras and true 3D profile measurement eliminate blind spots even on complex automotive and smartphone assemblies.

TR7500 SIII 3D inspection range covers everything from basic SMT components to large thru-hole capacitors, switches, connectors and hidden solder joints.

#### Wide Range 3D Inspection

Military grade blue laser sensors go beyond other 3D technology boundaries. Their height measurement range ensures that components up to 20 mm high can be inspected with maximum precision.

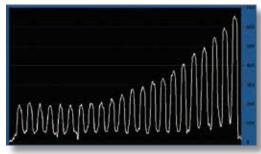
Laser sensors are an effective solution for polished bare silicon chips and wafer level packages. They also eliminate problems with black components on low contrast background.



#### Complete 3D PCB Assembly Inspection

Interactive 3D models help operators quickly review found defects, such as lifted components, IC leads, connectors, switches and other mounted devices for enhanced post-reflow inspection.

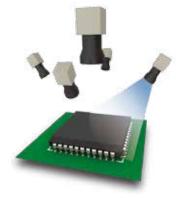


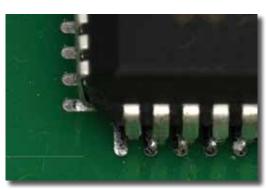


IC lead inspection using 2D + 3D technologies efficiently reveals lifted leads

#### Reveal Hidden Defects in Clear Angle View Images

Angle view images reveal soldering issues from another perspective, not available in single camera systems, and help eliminate an important source of defects.

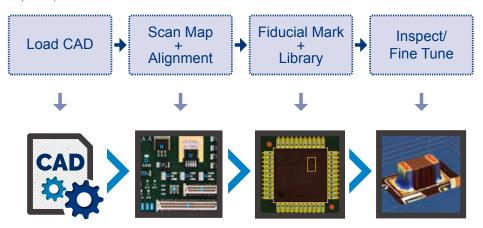




Hidden soldering defects revealed in side view

#### From CAD to Inspection in Minutes

TRI's intuitive software and smart component libraries streamline new product introduction in a few simple steps.



TRI AOI programming flow in a few simple steps

#### Intuitive Inspection Results

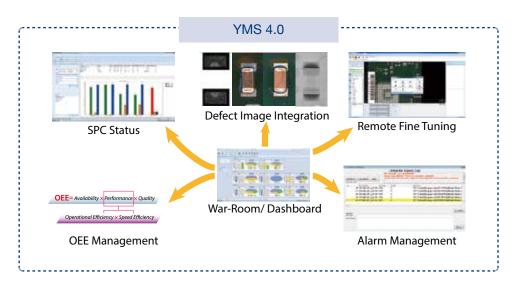
Reviewing defects on TR7500 SIII 3D is a breeze with intuitive height profile visualization.



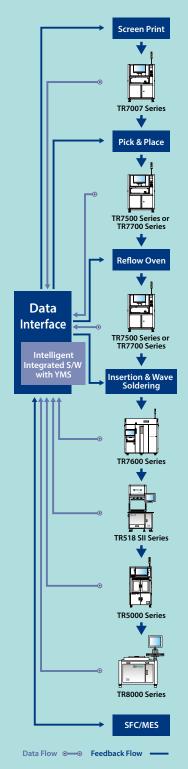
Easy to identify defects shown in specialized display modes

#### Industry 4.0 Production Line Integration

YMS 4.0 lets TRI inspection solutions interface and share inspection data with the shop floor system and other inspection machines. With the central console an operator can control, track, analyze and optimize the inspection process across the entire production line and obtain real actionable data to optimize production quality in the Industry 4.0 environment.



#### Yield Management System



- Inspection results and data integration
- Real time SPC and production yield management
- Quality reports and closed loop tracking
- Support defect component analysis and improvements
- Knowledge Management (KM)
- Productivity and Quality Management

#### SPECIFICATIONS

#### Optical & Imaging System

Top View Camera	4 Mpix high speed color camera
4 Angled View Cameras	1.3 or 6.5 Mpix (factory setting)
3D Laser Sensor	Dual 3D laser sensors
Lighting	Multi-phase RGB+W LED
Optical Resolution*	10 μm/15 μm
Laser Resolution*	10 µm (optional)/20 µm/50 µm
Imaging Method	Dynamic imaging with true 3D profile measurement
3D Inspection Range	20 mm

<sup>\*</sup> Factory setting

#### Imaging/Inspection Speed

Mode	2D	2D+3D
15 µm (cm²/sec)	120	40 - 60**
10 μm (cm²/sec)	60	27 - 39**

<sup>\*\*</sup> Depending on board size and laser resolution

#### Pre-/Post-Reflow Inspection Functions

Component	Missing, Tombstoning, Billboarding, Polarity, Rotation, Shift, Wrong Marking (OCV), Defective, Upside Down, Lifted Component, Extra Component, Foreign Material
Solder Joint	Excess Solder, Insufficient Solder, Bridging, Through-hole Pins, Lifted Lead, Golden Finger Scratch/Contamination

#### X-Y Table & Control

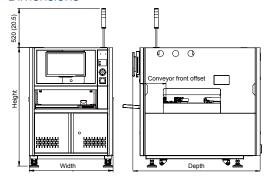
Ballscrew + AC servo with Motion Controller

X-Y Axis Resolution 1 μm PCB & Conveyor System

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	TR7500 SIII 3D	TR7500L SIII 3D	TR7500 SIII 3D DL
PCB Size	50 x 50 – 510 x 460 mm (1.97 x 1.97 – 20.1 x 18.1 in.)	50 x 50 – 660 x 460 mm (1.97 x 1.97 – 26.0 x 18.1 in.)	50 x 50 - 510 x 250 mm x 2 lanes (1.97 x 1.97 - 20.1 x 9.84 in. x 2 lanes) 50 x 50 - 510 x 550 mm x 1 lane (1.97 x 1.97 - 20.1 x 21.7 in. x 1 lane)
PCB Thickness	0.6 – 5 mm		
PCB Transport Height	880 – 920 mm (34.6 – 36.2 in.)		
Max. PCB Weight	3 kg ( 6.61 lbs)		
PCB Carrier/Fixing	Step motor driven conveyor & pneumatic clamping		
Clearance			
Тор	15 mm (0.59 in.) / 25 mm (0.98 in.) / 48 mm [(1.89 in.) optional**]		
Bottom	40 mm (1.58 in.)		
Edge	3 mm (0.12 in.)		

<sup>\*\* (1)</sup> Top clearance for laser resolution @ 50 µm is 25 or 48 mm (optional)

#### **Dimensions**



	TR7500 SIII 3D	TR7500L SIII 3D	TR7500 SIII 3D DL			
Width	1100 (43.3)	1300 (51.2)	1100 (43.3)			
Depth	1670 (65.7)	1630 (64.2)	1770 (69.7)			
Height	1550 (61.0)	1655 (65.2)	1550 (61.0)			
Conveyor front offset	335 (13.2)	365 (14.4)	335 (13.2)			
Weight	1010 kg (2227 lbs)	1250 kg (2756 lbs)	1150 kg (2530 lbs)			
Power	200 - 240 VAC, single phase,					
Requirement	50/60 Hz, 3 kVA					
Air	72 psi - 87 psi (5 - 6 bar)					

Unit : mm (in.)

#### **Options**

Barcode Scanner, Offline Editor, OCR, Yield Management System (YMS 4.0), YMS Lite

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#### Test Research, Inc.

7F., No.45, Dexing West Rd.,

#### **Headquarters**

Shilin Dist., Taipei City 11158, Taiwan TEL: +886-2-2832-8918 FAX: +886-2-2831-0567 E-Mail: sales@tri.com.tw http://www.tri.com.tw

#### Linkou, Taiwan

No.256, Huaya 2nd Rd., Guishan Dist., Taoyuan City 33383, Taiwan TEL: +886-2-2832-8918 FAX: +886-3-328-6579

#### Hsinchu, Taiwan

7F., No.47, Guangming 6th Rd., Zhubei City, Hsinchu County 30268, Taiwan TEL: +886-2-2832-8918 FAX: +886-3-553-9786

#### Shenzhen, China

5F.3, Guangxia Rd., Shang-mei-lin Area, Fu-Tian Dist., Shenzhen, Guangdong, 518049, China TEL: +86-755-83112668 FAX: +86-755-83108177 E-mail: shenzhen@cn.tri.com.tw

#### Suzhou, China

B Unit, Building 4, 78 Xinglin St., Suzhou Industrial Park, 215123, China TEL: +86-512-68250001 FAX: +86-512-68096639 E-mail: suzhou@cn.tri.com.tw

#### Shanghai, China

Room 6C, Building 14, 470 Guiping Rd., Xuhui Dist., Shanghai, 200233, China TEL: +86-21-54270101 FAX: +86-21-64957923 E-mail: shanghai@cn.tri.com.tw

#### USA

832 Jury Court, Suite 4, San Jose, CA 95112 U.S.A TEL: +1-408-567-9898 FAX: +1-408-567-9288 E-mail: triusa@tri.com.tw

#### **Europe** O'Brien Strasse 14

Germany TEL: +49-9122-631-2127 FAX: +49-9122-631-2147 E-mail: trieurope@tri.com.tw

91126 Schwabach

#### Japan

2-9-9 Midori, Sumida-ku, Tokyo, 130-0021 Japan TEL: +81-3-6273-0518 FAX: +81-3-6273-0519 E-mail: trijp@tri.com.tw

#### Korea

No.207 Daewoo-Technopia, 768-1 Wonsi-Dong, Danwon-Gu, Ansan City, Gyeonggi-Do, Korea TEL: +82-31-470-8858 FAX: +82-31-470-8859 E-mail: trikr@tri.com.tw

#### Malaysia

C11-1, Ground Floor, Lorong Bayan Indah 3 Bay Avenue, 11900 Bayan Lepas Penang, Malaysia

TEL: +604-6461171 E-mail: trimy@tri.com.tw

<sup>(2)</sup> Top clearance for laser resolution @ 20 µm is 25 mm

<sup>(3)</sup> Top clearance for laser resolution @ 10 µm is 15 mm